



### Electrical Performance

Parameter		Min.	Typ.	Max.	Units	Notes
Output frequency		1.544		106.25	MHz	As specified
Supply voltage		+4.5	+5.0	+5.5	V	
Supply current, output enabled				27	mA	1.544 to 32 MHz
				50		>32 to 50 MHz
				65		>50 to 106.25 MHz
Frequency stability				±20 to ±50	ppM	See Note 1 below
Operating temperature		-40		+85	°C	As specified
Output logic 0, VOL				10% V <sub>DD</sub>	V	HCMOS
				+0.4	V	TTL
Output logic 1, VOH		90% V <sub>DD</sub>			V	HCMOS
		+3.9			V	TTL
Output load				50	pF	HCMOS up to <50 MHz
				30	pF	HCMOS 50 to <70 MHz
				15	pF	HCMOS 70 to 106.25 MHz
				10	TTL	TTL
Duty cycle	1.544 to 80 MHz	45		55	%	-40 to +85°C measured 50%VDD
	>80 to 106.25 MHz	45		55	%	-10 to +70°C measured 50%VDD
		40		60	%	-40 to +85°C measured 50%VDD
	1.544 to 106.25 MHz	40		60	%	-40 to +85°C measured 1.5V
Rise and fall time	1.544 up to <50 MHz			8	ns	measured 20/80% of waveform
	50 to <70 MHz			5	ns	
	70 to 106.25 MHz			3	ns	
	1.544 to <70 MHz			5	ns	measured 0.4V to 2.4V
	70 to 106.25 MHz			2	ns	

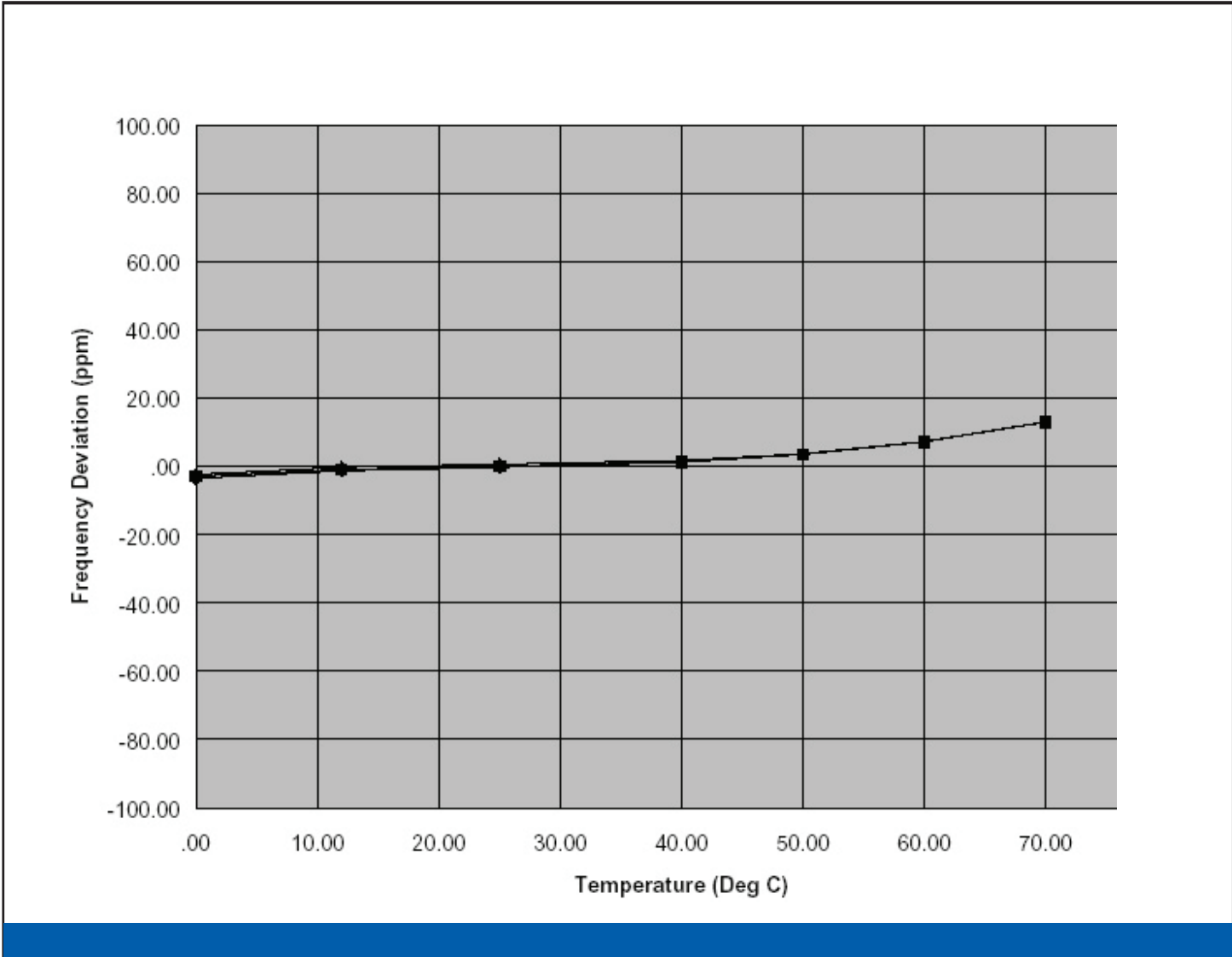
#### Notes:

- As specified. Stability includes all combinations of operating temperature, load changes, rated input (supply) voltage changes, initial calibration tolerance (25°C), aging (1 year at 25°C average effective ambient temperature), shock and vibration.
- For specifications other than those listed, please contact sales.

### Output Enable / Disable Function

Parameter	Min.	Typ.	Max.	Units	Notes
Input Voltage (pin 1), Output Enable	2.2			V	or open
Input voltage (pin 1), Output Disable (low power standby)			0.8	V	Output is Hi-Z
Internal pullup resistance	50			kΩ	
Output disable delay			100	ns	
Output enable delay			100	ns	

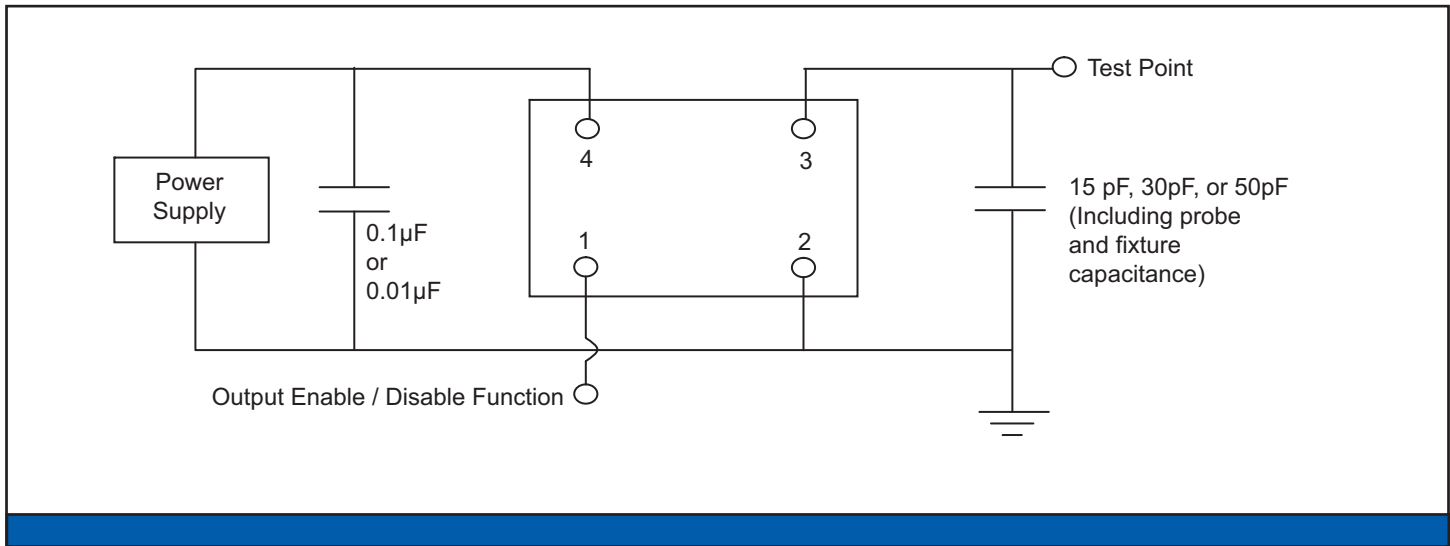
Typical Frequency Stability



### Absolute Maximum Ratings

Parameter	Min.	Typ.	Max.	Units	Notes
Storage temperature	-55		+125	°C	

### Test Circuit

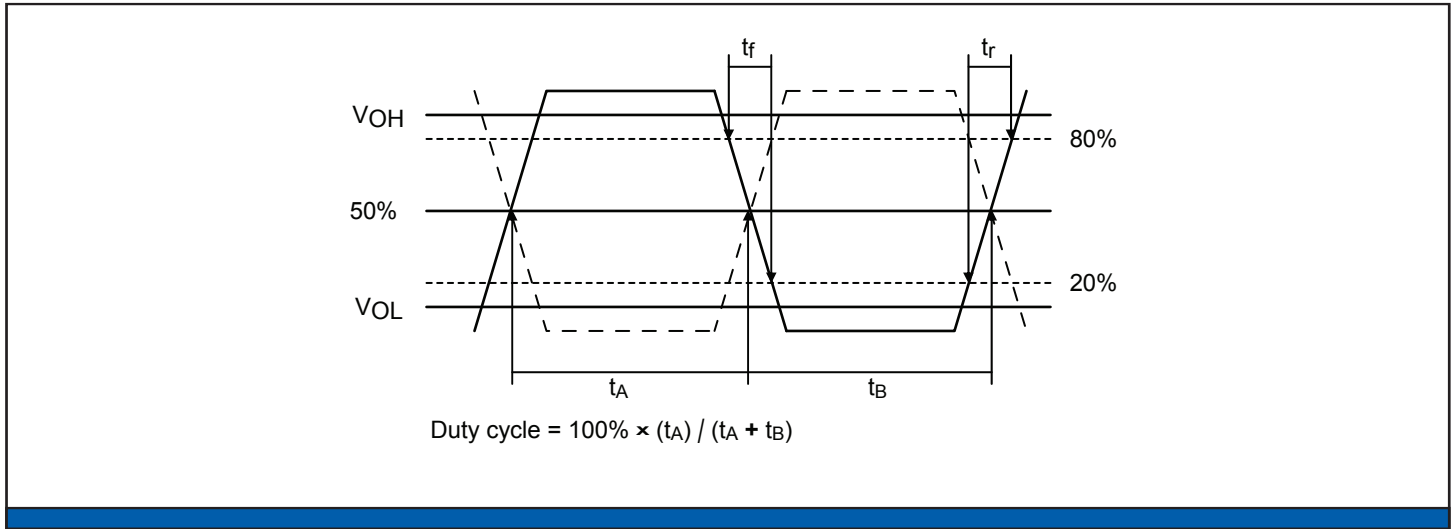


### Reliability Test Ratings

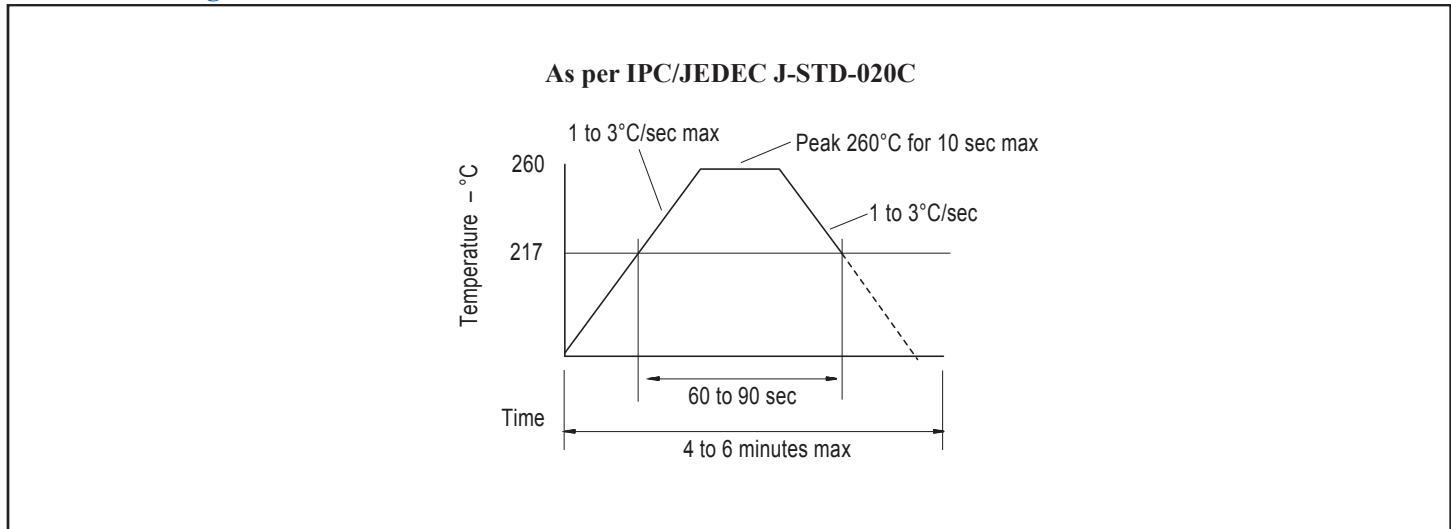
This product is rated to meet the following test conditions:

Type	Parameter	Test Condition
Mechanical	Shock	MIL-STD-883, Method 2002, Condition B
Mechanical	Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Mechanical	Terminal strength	MIL-STD-883, Method 2004, Condition D
Mechanical	Gross leak	MIL-STD-883, Method 1014, Condition C
Mechanical	Fine leak	MIL-STD-883, Method 1014, Condition A2 ( $R_1 = 2 \times 10^{-8}$ atm cc/s)
Mechanical	Solvent resistance	MIL-STD-202, Method 215
Environmental	Thermal shock	MIL-STD-883, Method 1011, Condition A
Environmental	Moisture resistance	MIL-STD-883, Method 1004
Environmental	Vibration	MIL-STD-883, Method 2007, Condition A
Environmental	Resistance to soldering heat	J-STD-020C Table 5-2 Pb-free devices (2 cycles max)

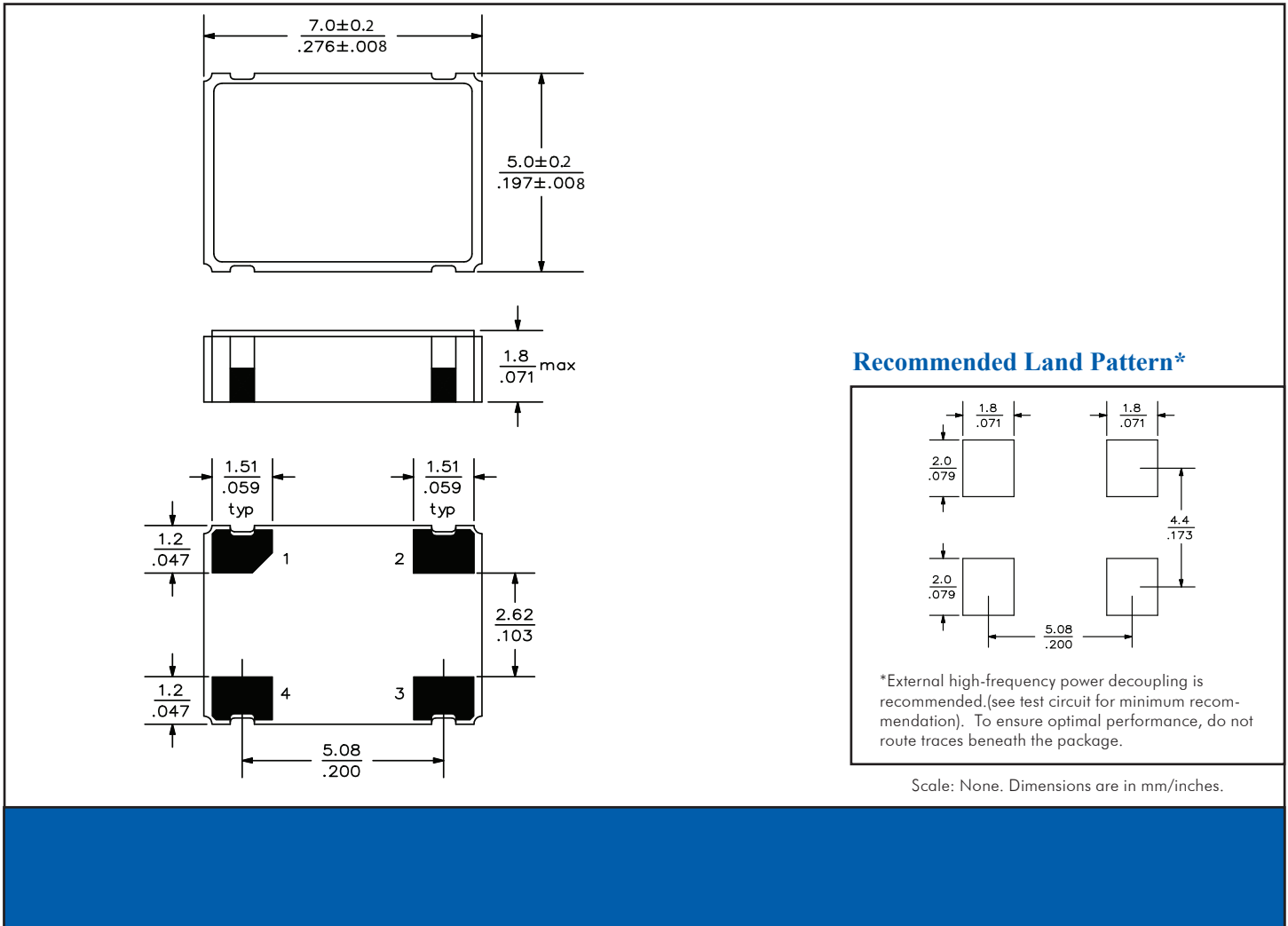
Output Waveform



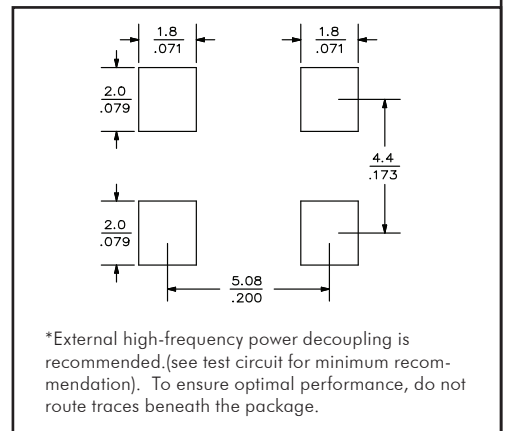
Reflow Soldering Profile



Mechanical Drawings



Recommended Land Pattern\*



\*External high-frequency power decoupling is recommended. (see test circuit for minimum recommendation). To ensure optimal performance, do not route traces beneath the package.

Scale: None. Dimensions are in mm/inches.